

Silicon N Channel Power MOSFET

Description

The HXN10B5 is n-channel power trench MOSFET with latest technology. So fast switching speed and low on-resistance. Usually used at power switching application . It is also intended for any applications with low gate drive requirements .

Features

- Latest Trench Power MOSFET technology
- Low On-state Resistance
- High Current Density
- Low Gate Charge
- 100% UIS Test

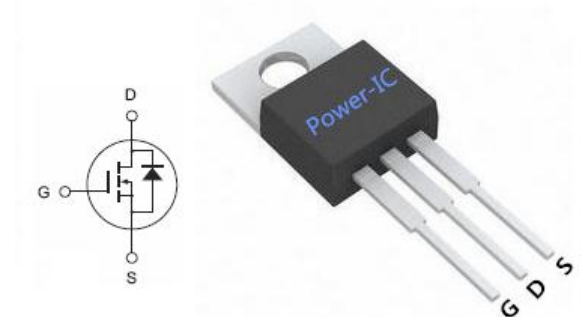
Product Summary

| BVDS | RDSON | ID |
|------|-------|------|
| 100V | 6.2mΩ | 150A |

Applications

- Motor Driver
- Power Management

TO-220 Package



1、 Absolute maximum ratings

| Symbol | Parameter | Value | Unit |
|----------------|--|-------|------|
| V_{DS} | Drain-source voltage ($V_{GS} = 0$) | 100 | V |
| V_{GS} | Gate-source voltage | ±25 | V |
| $I_D^{(1)}$ | Drain current (continuous) at $T_C = 25\text{ }^\circ\text{C}$ | 150 | A |
| $I_{DM}^{(2)}$ | Drain current (pulsed) | 560 | A |

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| | | | |
|----------------|---|------------|------------------|
| P_D | Power dissipation at $T_C = 25\text{ }^\circ\text{C}$ | 350 | W |
| $E_{AS}^{(3)}$ | Single pulse avalanche energy | 1800 | mJ |
| T_j | Operating junction temperature | -55 to 150 | $^\circ\text{C}$ |

1. Current limited by package
2. Pulse width limited by safe operating area
3. Starting $T_j = 25\text{ }^\circ\text{C}$, $I_D = 60\text{A}$, $V_{DD} = 30\text{V}$, $L = 1\text{mH}$

2、 Thermal data

| Symbol | Parameter | Min. | Typ. | Max. | Unit |
|-----------------|-------------------------------------|------|------|------|---------------------------|
| $R_{\theta JA}$ | Thermal Resistance Junction-Ambient | | 62.5 | | $^\circ\text{C}/\text{W}$ |
| $R_{\theta JC}$ | Thermal Resistance Junction-Case | | 0.5 | | $^\circ\text{C}/\text{W}$ |

3、 Electrical characteristics

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|---------------|---------------------------|---|------|------|-----------|---------------|
| $V_{(BR)DSS}$ | Drain-source breakdown | $I_D = 250\text{ }\mu\text{A}$, $V_{GS} = 0$ | 100 | | | V |
| I_{DSS} | Zero gate voltage drain | $V_{DS} = \text{Max rating}$ | | | 1 | μA |
| I_{GSS} | Gate body leakage current | $V_{GS} = \pm 25\text{V}$ | | | ± 100 | nA |
| $V_{GS(th)}$ | Gate threshold voltage | $V_{DS} = V_{GS}$ | 2 | 3 | 4 | V |
| $R_{DS(on)}$ | Static drain-source on | $V_{GS} = 10\text{V}$ | | 6.2 | | m Ω |
| C_{iss} | Input capacitance | $V_{DS} = 25\text{V}$ | | 9500 | | pF |
| C_{oss} | Output capacitance | $f = 1\text{ MHz}$ | | 560 | | pF |
| C_{rss} | Reverse transfer | $V_{GS} = 0$ | | 350 | | pF |
| Q_g | Total gate charge | $V_{DD} = 30\text{V}$ | | 145 | | nC |
| Q_{gs} | Gate-source charge | $I_D = 40\text{A}$ | | 40 | | nC |
| Q_{gd} | Gate-drain charge | $V_{GS} = 10\text{V}$ | | 29 | | nC |
| I_{SD} | Source-drain current | | | | 150 | A |

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| | | | | | | |
|-----------------|----------------------------------|----------------------------|--|--|-----|---|
| $I_{SDM}^{(1)}$ | Source-drain current (pulsed) | | | | 560 | A |
| $V_{SD}^{(2)}$ | Forward on voltage | $I_{SD} = 98A, V_{GS} = 0$ | | | 1.2 | V |

1. Pulse width limited by safe operating area
2. Pulsed: pulse duration=300 μ s, duty cycle 1.5%